

Title (en)

MATERIAL FOR ELECTRIC CONTACTS BASED ON SILVER-TIN OXIDE OR SILVER-ZINC OXIDE AND PROCESS FOR ITS PRODUCTION

Title (de)

WERKSTOFF FÜR ELEKTRISCHE KONTAKTE AUF DER BASIS VON SILBER-ZINNOXID ODER SILBER-ZINKOXID UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)

MATERIAU POUR CONTACTS ELECTRIQUES A BASE D'ARGENT-OXYDE STANNIQUE OU D'ARGENT-OXYDE DE ZINC ET SON PROCEDE DE FABRICATION

Publication

EP 0660964 B1 19960626 (DE)

Application

EP 93920746 A 19930916

Priority

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Abstract (en)

[origin: DE4331526A1] Electric contact material is made by mixing together a powder of silver or mainly silver-containing alloy with tin oxide powder plus 0.01-10 wt.% (based on the amount of tin oxide) of an additive powder containing compounds including silver, oxygen, metals from sub-groups II to VI of periodic table and/or antimony, bismuth, germanium, indium and gallium. The mixture is pressed together and sintered. The powder mixture contains 5-20, pref. 8-14 wt.% tin oxide and 0.1-2.5 wt.%, pref. max. 1 wt.% of additive material. The additive material contains one from tungsten, molybdenum, vanadium, antimony, bismuth and germanium. Molybdenum is esp. favoured. ADVANTAGE - In addition to having a longer working life, the contact body has good properties when under a heated condition and is ductile and so can be worked without fear of cracking.

IPC 1-7

H01H 1/02

IPC 8 full level

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